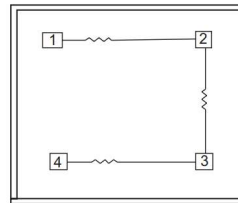


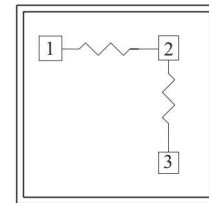
### Features

- Withstand high current
- Small size
- One chip can be with different resistances
- Can customize according to requirements

### Function Diagram



BW520



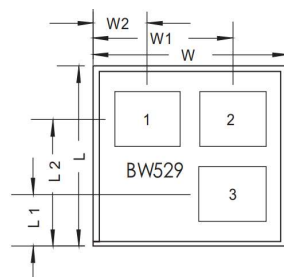
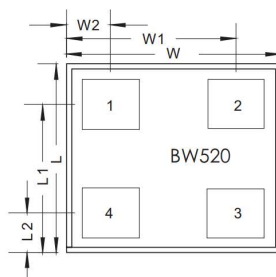
BW529

### Electrical Specifications (Ta=+25°C, 50Ω system)

Part Number	W	W1	W2	L	L1	L2	Standard Resistance (Ω)			
	um	um	um	um	um	um	1→2	2→3	1→3	1→4
BW520	580	450	120	580	450	120	50	50	100	150

Part Number	W	W1	W2	L	L1	L2	Standard Resistance (Ω)		
	um	um	um	um	um	um	1→2	2→3	1→3
BW529	400	280	110	400	270	120	20	10	30

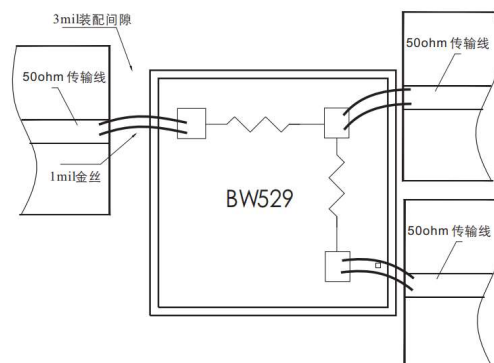
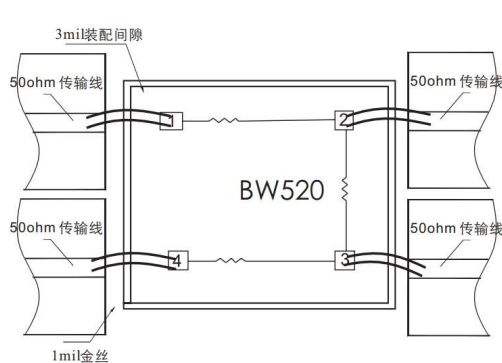
### Outline Size



### Note:

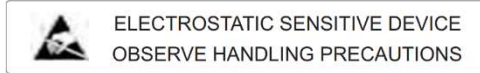
1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size: 100\*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Application



### Absolute Rating

Max. Handling current	100mA
Junction Temperature	175°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C



### Bonding Definition

#### BW520

Number	Symbol	Description
1、 2、 3、 4	In, Out	Any two ports can be used as input or output
	GND	Bottom must be grounded

#### BW529

Number	Symbol	Description
1、 2、 3	In, Out	Any two ports can be used as input or output
	GND	Bottom must be grounded